



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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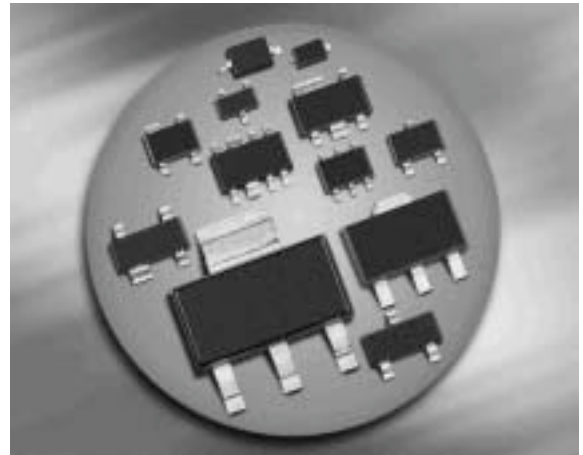
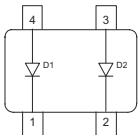
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Silicon Switching Diode

- Electrically insulated high-voltage medium-speed diodes
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101


BAW101


Type	Package	Configuration	Marking
BAW101	SOT143	parallel	JP _s

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	300	V
Peak reverse voltage	V_{RM}	300	
Forward current	I_F	250	mA
Peak forward current	I_{FM}	500	
Peak forward current	I_{FM}	500	mA
Surge forward current, $t = 1 \mu\text{s}$	I_{FS}	4.5	A
Non-repetitive peak surge forward current	I_{FSM}	-	
Total power dissipation $T_S \leq 35^\circ\text{C}$	P_{tot}	350	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

¹Pb-containing package may be available upon special request

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BAW101	R_{thJS}	≤ 330	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

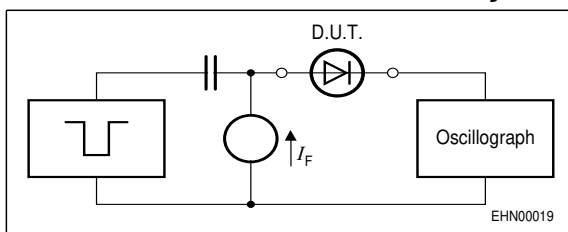
Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Breakdown voltage $I_{(BR)} = 100 \mu\text{A}$	$V_{(BR)}$	300	-	-	V
Reverse current $V_R = 250 \text{ V}$ $V_R = 250 \text{ V}, T_A = 150 \text{ }^\circ\text{C}$	I_R	-	-	0.15 50	μA
Forward voltage $I_F = 100 \text{ mA}$	V_F	-	-	1.3	V

AC Characteristics

Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	6	-	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}$, measured at $I_R = 1 \text{ mA}$, $R_L = 100 \Omega$	t_{rr}	-	1	-	μs

Test circuit for reverse recovery time


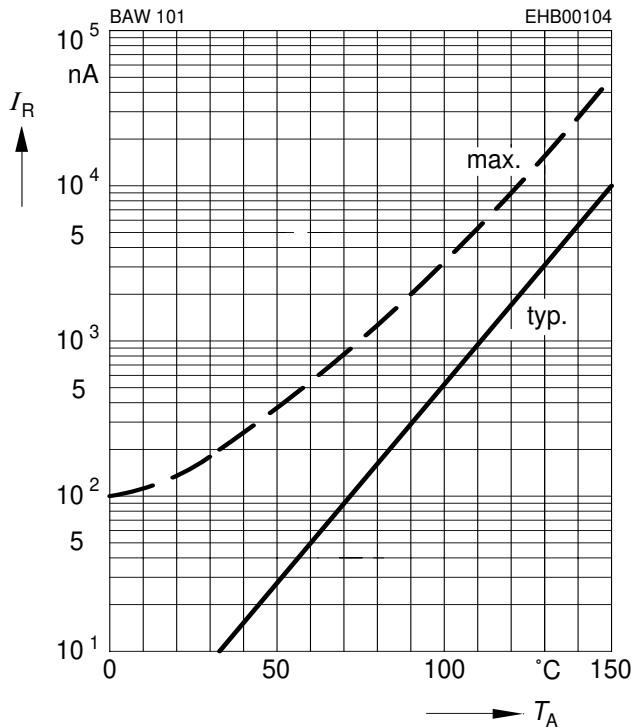
Pulse generator: $t_p = 10 \mu\text{s}$, $D = 0.05$, $t_r = 0.6 \text{ ns}$,
 $R_i = 50 \Omega$

Oscilloscope: $R = 50 \Omega$, $t_r = 0.35 \text{ ns}$, $C \leq 1 \text{ pF}$

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

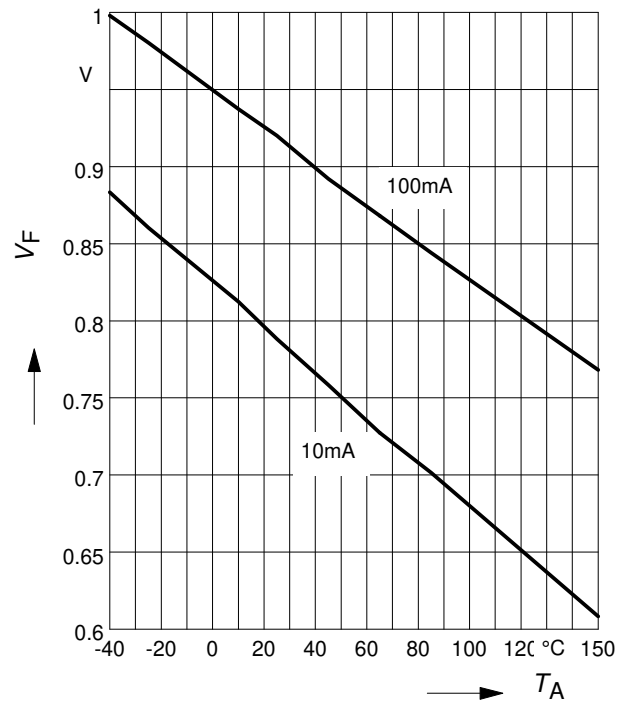
Reverse current $I_R = f(T_A)$

$V_R = 250V$



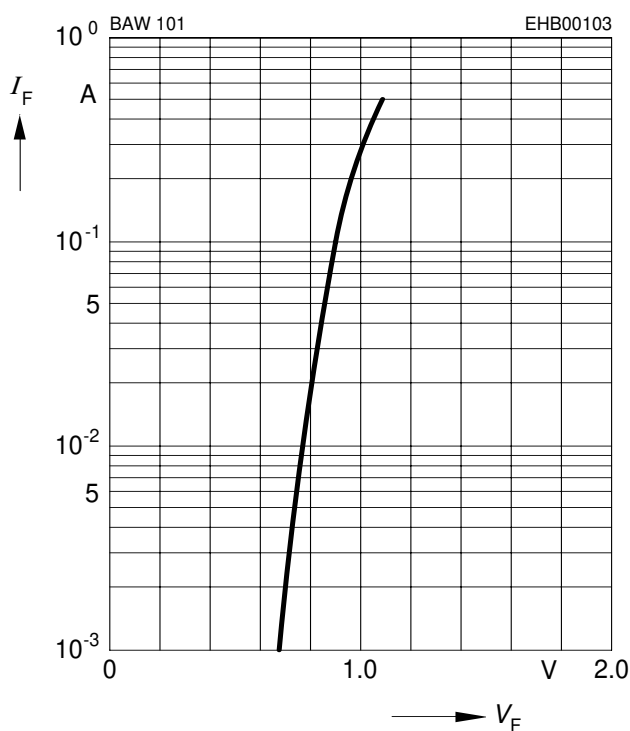
Forward Voltage $V_F = f(T_A)$

$I_F = \text{Parameter}$



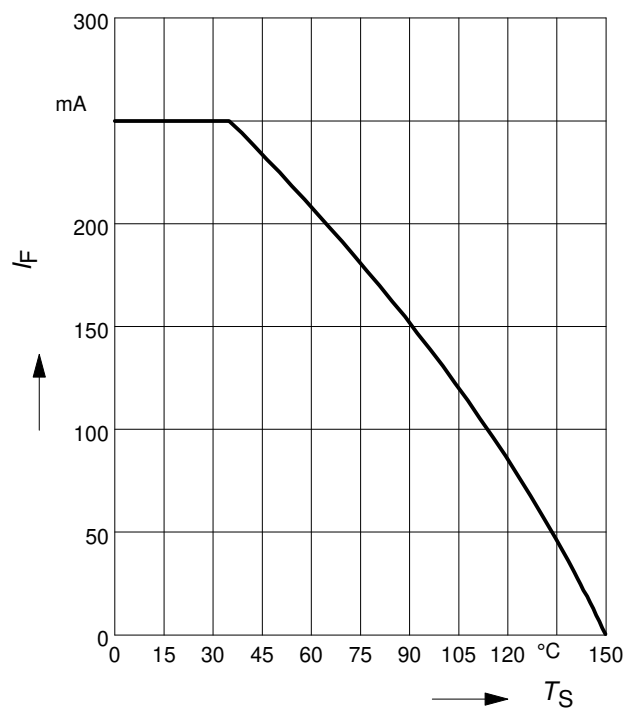
Forward current $I_F = f(V_F)$

$T_A = 25^\circ C$

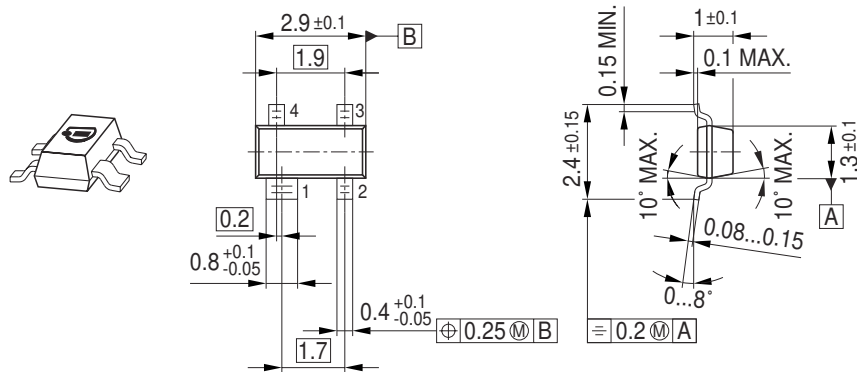


Forward current $I_F = f(T_S)$

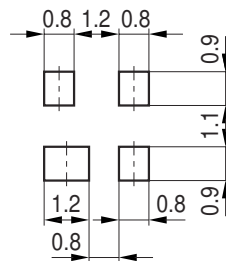
BAW101



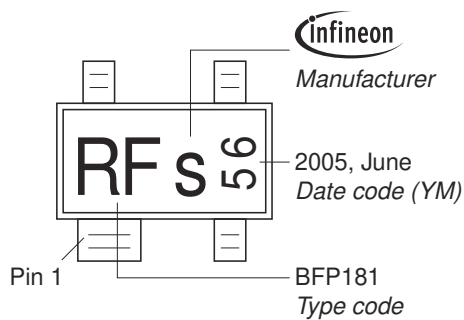
Package Outline



Foot Print

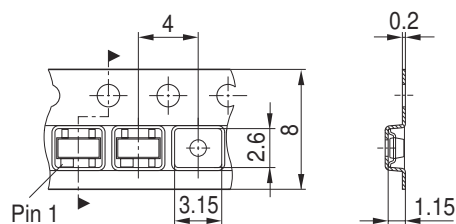


Marking Layout (Example)



Standard Packing

Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
 Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



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